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## (54) ELECTRONIC APPARATUS COOLING DEVICE, WATER-COOLED INFORMATION PROCESSING DEVICE, COOLING MODULE, AND ELECTRONIC APPARATUS COOLING **METHOD**

- (71) Applicant: NEC Corporation, Minato-ku, Tokyo
- (72) Inventor: Yoichi MIZUKO, Tokyo (JP)
- (73) Assignee: **NEC Corporation**, Minato-ku, Tokyo
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#### ABSTRACT (57)

An electronic apparatus cooling device is provided with a water-cooling cold plate unit that is disposed in contact with a heat-generating element and that cools the heat-generating element directly by means of a liquid refrigerant that circulates in an inner flow path; an air-cooling fin disposed adjacent or in proximity to the water-cooling cold plate unit and having a fin tube through which the liquid refrigerant is circulated; and a refrigerant supply means that supplies the liquid refrigerant to the inner flow path of the water-cooling cold plate unit and to the fin tube in the air-cooling fin in a distributed manner.

